

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10754381			
<b>Filing Date:</b>	09-Jan-2004			
<b>Title of Invention:</b>	LAYERED SUPPORT AND METHOD FOR LAMINATING CMP PADS			
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<b>Filer:</b>	David Schnapf/Jordan Wilson			
<b>Attorney Docket Number:</b>	02JC-105385			
Filed as Small Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
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Utility Appl issue fee	2501	1	700	700
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1000